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FIRST NAMED INVENTOR ATTORNEY DOCKET NO. APPLICATION NO. **FILING DATE** 09/023,146 02/12/98 SANDHU 336905 (91-36

MM12/1228 T

EXAMINER

DANG.T

PAPER NUMBER **ART UNIT**

2823

DATE MAILED:

12/28/99

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

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Application No. 09/023,146

Applicant(s)

Sandhu

Office .	Action	Summary
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Examiner
Trung Dang

Group Art Unit 2823

Responsive to communication(s) filed on Jul 12, 1999	
★ This action is FINAL.	
Since this application is in condition for allowance except for in accordance with the practice under <i>Ex parte Quayle</i> , 193	
A shortened statutory period for response to this action is set to is longer, from the mailing date of this communication. Failure application to become abandoned. (35 U.S.C. § 133). Extens 37 CFR 1.136(a).	to respond within the period for response will cause the
Disposition of Claims	
	is/are pending in the application.
Of the above, claim(s)	is/are withdrawn from consideration.
Claim(s)	
Claim(s)	
☐ Claims	
Application Papers	
☐ See the attached Notice of Draftsperson's Patent Drawin	ng Review, PTO-948.
☐ The drawing(s) filed on is/are object	cted to by the Examiner.
☐ The proposed drawing correction, filed on	is 🗀 pproved 🗀 disapproved.
☐ The specification is objected to by the Examiner.	
$\hfill\Box$ The oath or declaration is objected to by the Examiner.	
Priority under 35 U.S.C. § 119	
Acknowledgement is made of a claim for foreign priority	under 35 U.S.C. § 119(a)-(d).
☐ All ☐ Some* ☐ None of the CERTIFIED copies of	of the priority documents have been
☐ received.	
received in Application No. (Series Code/Serial Nu	mber)
\square received in this national stage application from the	e International Bureau (PCT Rule 17.2(a)).
*Certified copies not received:	·
☐ Acknowledgement is made of a claim for domestic prior	ity under 35 U.S.C. § 119(e).
Attachment(s)	
☐ Notice of References Cited, PTO-892	
☐ Information Disclosure Statement(s), PTO-1449, Paper N	lo(s)
☐ Interview Summary, PTO-413	40
□ Notice of Draftsperson's Patent Drawing Review, PTO-9	48
☐ Notice of Informal Patent Application, PTO-152	
SEE OFFICE ACTION ON	THE FOLLOWING PAGES

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1. Claims 1-47 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention.

The instant application discloses a method for depositing tungsten silicide films characterized by the formula WSi_x. However, without defining or specifying numerical values of x, one cannot determine the final product so that the invention can be practiced. Would it be WSi, WSi_{1.2}, WSi_{1.5}, WSi₂, or any amount of Si in the tungsten silicide film? The specification, therefore, does not contain a written description of the invention in a full, clear, and concise manner as required by the first paragraph of 35 U.S.C § 112.

2. Claims 33-38 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

The limitation "the discontinuous nucleation layer" recited at the 4th line of claim 33 lacks antecedent basis. Note that since it is unclear as to which

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"discontinuous nucleation layer" applicant makes reference to, the rejection over prior art of claims 33-38 can not be made at this time.

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1, 2, 4, 5, 8, 9, 12-19, and 21 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kawanishi et al. (English translation of JP-39528, cited by applicant) taken with Price et al.

Kawanishi teaches a process for depositing a tungsten silicide film on a substrate which comprises the steps of: forming a nucleation layer of tungsten silicide (WSi₂) on the substrate using a CVD process with silane (SiH₄) silicon source gas and a reactant gas of tungsten hexafluoride (WF₆) at a temperature of 360°C; depositing a WSi₂ film on the nucleation layer by CVD using dichlorosilane

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(SiH₂Cl₂) silicon source gas and WF₆ reactant gas at a temperature of 680°C. See pages 6-7.

The difference between Kawanishi and the claims is in the deposition temperature of which the WSi₂ film is deposited using SiH₂Cl₂ and WF₆.

However, Price et al. teaches that once a <u>nucleation layer</u> of tungsten disilicide was formed by initiating a plasma discharge in a short time, tungsten disilicide (WSi₂) can be deposited by CVD from a mixture of SiH₂Cl₂ and WF₆ at a temperature in a range of 390-400°C <u>without the presence of plasma</u>. See col. 6, lines 53-54 in conjunction with col. 5, lines 54-68; col. 9, lines 1-12, and Fig. 6.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Kawanishi's teachings by depositing the WSi₂ film on the nucleation layer at a temperature in a range of 390-400°C because of the followings:

a) It is known that once a temperature above the dissociation temperature of reactive gases (critical temperature Tc) is reached, the deposition rate varies gradually with temperature change hence the control of temperature is not critical for film thickness control so long as a minimum deposition temperature is exceeded.

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See Price col. 5, lines 66-68; col. 6, lines 20-27. Thus, one skill in the art would find it obvious to deposit the WSi₂ film of Kawanishi at the temperature range suggested by Price because lower temperature deposition would be beneficial in that thermal budget is reduced while assuring substantially the same deposition characteristics (e.g. temperature/deposition rate independency, film thickness uniformity) as the film is deposited at 680°C.

b) It is known, as shown in Price that once a <u>nucleation layer</u> of tungsten disilicide was formed by initiating a plasma discharge in a short time, a WSi₂ film can be deposited in a range of 390-400°C with a rapid deposition rate and a good uniformity without the presence of plasma (col. 9, lines 1-20). Thus, it would have been obvious that, in the process of Kawanishi, once a nucleation layer has been formed, a WSi₂ film can be deposited at a temperature range of 390-400°C as suggested by Price because the application of an old process to make the same would have been within the level of an artisan.

As for claim 14, the Examiner takes official notice that Argon, Nitrogen, or Helium is known individually as a carrier gas. Since each member of the claimed

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mixture is known individually as a carrier gas, one of ordinary skill in the art would expect such mixture to function as a carrier gas in an additive or cumulative manner.

As for claims 13 and 15, the selection of deposition time and flow rates of reactive gases is not inventive since it has been held that discovery an optimum value of a result effective variable involves only routine skilled in the art. In re Boesch, 617 F.2d 272, 205 USPQ 215 (CCPA 1980).

As for claims 16 and 17, the combined rejection meets the claimed limitation in that 360°C is considered substantially equivalent to 390°C.

4. Claims 3, 6, 7, 10, 11, 20, 22, and 23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kawanishi taken with Price as applied to claims 1, 2, 4, 5, 8, 9, 12-19, 21 above, and further in view of Brors et al. (U.S. Pat. 4,565,157 cited by applicant)

The combination of Kawanishi and Price teaches a process as noted above with the exception that the references do not specifically mention that the WSi2 film is deposited using a cold wall CVD system as claimed, although Kawanishi does

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suggest that any existing CVD apparatus can be used with the same effect (page 11, lines 13-15).

Brors teaches that deposition of WSi₂ using a cold wall CVD system with premix chambers is advantageous over conventional hot wall CVD system in that a deposited film with high quality and uniformity can be obtained. See line 53 of col. 2 to line 32 of col. 3; col. 4, lines 45-68; col. 7, lines 1-40.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to have deposited the WSi₂ film using the cold wall CVD system as suggested by Brors because doing such would obtain a film with high quality and uniformity.

As for claims 6 and 22, the Examiner takes official notice that a carrier gas is conventionally used in the deposition of tungsten silicide. Also see col. 4, lines 45-50 in Brors for the mixing of a silicon source gas, a reactant gas, and a carrier gas in a mixing chamber 28.

As for claims 7 and 23, the selection of a flow rate as claimed is not inventive since it has been held that discovery an optimum value of a result effective

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variable involves only routine skilled in the art. In re Boesch, 617 F.2d 272, 205 USPQ 215 (CCPA 1980).

5. Applicant's arguments filed 7/12/99 have been fully considered but they are not persuasive.

With respect to the 112, first paragraph rejection, applicant argues that one having ordinary skill in the art of tungsten silicide deposition process would understand the chemical formula WSix to encompasses all form of tungsten silicide. The Examiner disagrees for the following reasons:

a) An enabling disclosure under 35 USC 112, first paragraph, is one which allows those skilled in the art to make and use the claimed invention without undue experimentation. Ex parte Singh 17 USPQ 2d 1714, 1715 (BPAI 1990); In re Wands 8 USPQ 2d 1400 (Fed. Cir. 1988); U. S. V. Telectronics Inc. 8 USPQ 2d 1217 (Fed. Cir. 1988). The desired stoichiometry of a tungsten silicide film having a general formula WSix is known to depend largely on the deposition conditions such as active gases flow rates, deposition temperature, etc., and the resulted silicide film possesses different electrical characteristic. Two references cited in

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the parent case SN 08/506952 make it evident that the deposition of WSix where x is between 2.0 and 4.0 (see Brors, U.S. Pat. 4,851,295) and where x is between 0.01 and 0.1 (see Ohba, U.S. Pat. 4,902,645) requires totally different deposition conditions. Thus, in order to form a WSix which encompasses all form of tungsten silicide, one having ordinary skill in the art would necessarily perform tremendous undue experimentations.

b) If applicant was allowed the protection of all form of tungsten silicide, this would prevent others from obtaining a new and useful composition of tungsten silicide.

Applicant also argues that the use of the language "consisting essentially of" renders the plasma ignition step of Price falls outside of the scope of claims 33-47. This argument is found irrelevant. Price reference was used a secondary reference provides the teaching that a tungsten silicide film can be deposited at a temperature range of 390-400°C without plasma, once a nucleation layer has been preformed. Applying Price's teaching to the process of Kawanishi with motivation as recited in

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the rejection which results in a combined process which does not include the plasma ignition step.

6. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, THIS ACTION IS MADE FINAL. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

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7. Any inquiry concerning this communication or earlier communications from

the examiner should be directed to Trung Dang whose telephone number is (703)

308-2548. The examiner can normally be reached on weekdays from 8:30AM to

5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the

examiner's supervisor, Wael Fahmy, can be reached on (703) 308-4918. The fax

phone number for this Group is (703) 305-3432 or (703) 308-7725.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the Group receptionist whose telephone number is

(703) 308-0956.

Trung Dang

Mung Dang

Primary Examiner, Group 2800